

	Hits	Search Text	DBs
48	12	((resist or photoresist) same (affinit\$4 or additive) same (solution or solvent) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4) same (resist or photoresist) same (affinit\$4) same (mix\$4)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
49	12	((resist or photoresist) same (affinit\$4 or additive) same (solution or solvent) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4) same (resist or photoresist) same (affinit\$4 or megaface) same (mix\$4)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
50	158	((resist or photoresist) same (affinit\$4 or additive) same (solution or solvent) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or solvent or solution) same additive same (mix\$4)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
51	12	((resist or photoresist) same (affinit\$4 or additive) same (solution or solvent) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or solvent or solution) same (surfactant or additive) same ((adjust\$4 near18 contact near12 angle) or hydrophilicize or wett\$6) same (mix\$4)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
52	0	((resist or photoresist) same (affinit\$4 or additive or surfactant or surface\$4active\$6agent or addend) same ((supply or feed) near20 (pipe or inlet or means)) same (solution or solvent) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or solvent or solution) same (surfactant or additive or (surface near12 active near12 agent)) same ((adjust\$4 near18 contact near12 angle) or hydrophiliciz\$4 or wett\$7) same (mix\$4)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
53	0	((resist or photoresist) same (affinit\$4 or additive or surfactant or surface\$4active\$6agent or addend) same ((supply or feed or pipe or inlet or means)) same (solution or solvent) same (substrate or wafer) same (apparatus or system)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or solvent or solution) same (surfactant or additive or (surface near12 active near12 agent)) same ((adjust\$4 near18 contact near12 angle) or hydrophiliciz\$4 or wett\$7) same (mix\$4)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
54	6	((resist or photoresist) same (affinit\$4 or additive or surfactant or surface\$4active\$6agent or addend) same ((supply or feed or pipe or inlet or means)) same (solution or solvent) same (substrate or wafer) same (apparatus or system)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or solvent or solution) same (surfactant or additive or (surface near12 active near12 agent))) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
55	1	((resist or photoresist) same (affinit\$4 or additive or surfactant or surface\$4active\$6agent or addend) same ((supply or feed or pipe or inlet or means)) same (mix\$5) same (solution or solvent) same (apparatus or system)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (substrate or workpiece or wafer) same (affinit\$4 or solvent or solution) same (surfactant or additive or (surface near12 active near12 agent) or addend)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
56	1	((resist or photoresist) same (affinit\$4 or additive or surfactant or (surface near12 active near12 agent) or addend) same (supply or feed or pipe or inlet or means) same mix\$5 same (solution or solvent) same (apparatus or system)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or solvent or solution) same (surfactant or additive or (surface near12 active near12 agent) or addend)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
57	2	118/52.ccls. and ((resist or photoresist) same (affinit\$4 or additive) same (solution or solvent) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or solvent or solution) same additive same (mix\$4)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
58	0	118/16.ccls. and ((resist or photoresist) same (affinit\$4 or additive) same (solution or solvent) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or solvent or solution) same additive same (mix\$4)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
59	0	118/52.ccls. and ((resist or photoresist) same (affinit\$4 or additive) same (solution or solvent) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or surfactant or (surface\$16agent)) same additive same (mix\$4)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
60	0	396/604.ccls. and ((resist or photoresist) same (affinit\$4 or additive) same (solution or solvent) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or surfactant or (surface\$16agent)) same additive same (mix\$4)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
61	0	396/611.ccls. and ((resist or photoresist) same (affinit\$4 or additive) same (solution or solvent) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or surfactant or (surface\$16agent)) same additive same (mix\$4)) and (expos\$4 or irradiat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
62	3	((resist or photoresist) same (affinit\$4 or additive or surfactant or surface\$4active\$6agent or addend) same ((supply or feed or pipe or inlet or means)) same (solution or solvent) same (substrate or wafer) same (apparatus or system)) and develop\$4 and ((coat\$4 or form\$4 or layer or deposit\$4 or film) same (resist or photoresist) same (affinit\$4 or solvent or solution) same (surfactant or additive or (surface near12 active near12 agent))) and (expos\$4 or irradiat\$4)	US-PGPUB